Electronic Pate	ent App	lication Fee	Transm	ittal			
Application Number:	105	10520141					
Filing Date:	01-	01-Sep-2005					
Title of Invention:	LAI	LARGE-DIAMETER SIC WAFER AND MANUFACTURING METHOD THEREOF					
First Named Inventor/Applicant Name:	Shi	Shigehiro Nishino					
Filer:	Chi	Christopher W. Brown/Tricia Aldrich					
Attorney Docket Number:	122	122261					
Filed as Large Entity	•						
U.S. National Stage under 35 USC 371 Fi	iling Fee	s					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:			<u> </u>				
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Utility Appl issue fee		1501	1	1510	1510		
Publ. Fee- early, voluntary, or normal		1504	1	300	300		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1810